

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	70	257/613-616.ccls. and @pd>"20050204"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:18
L2	256	438/613-616.ccls. and @pd>"20050204"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:23
L3	148	438/111,123.ccls. and @pd>"20050204"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:23
L4	26	((power adj2 device) or (power adj chip)) and leadframe and @pd>"20050204"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:26
L5	90	((power adj2 device) or (power adj chip)) and (solder adj (ball\$1 or bump\$1)) and @pd>"20050204"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:27
L6	67	(leadframe (lead adj frame)) and ((die chip) with MOSFET) and @pd>"20050204"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:37
L7	43	(leadframe (lead adj frame)) and ((die chip) with (MOSFET MOS)) and (bump bumps ball balls) and @pd>"20050204"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:35
L8	18	((leadframe (lead adj frame)) and ((die chip) with (MOSFET MOS)) and (bump bumps ball balls)).clm.	US-PGPUB	OR	ON	2005/10/15 18:35
L9	48	((leadframe (lead adj frame)) and ((die chip) with MOSFET)).clm.	US-PGPUB	OR	ON	2005/10/15 18:38
S1	9	257/738.ccls. and power adj device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:15

S2	18	257/738.ccls. and power adj2 device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 17:47
S3	22	257/778.ccls. and power adj2 device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 10:42
S4	56	257/713.ccls. and power adj2 device	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 10:46
S5	222	257/738.ccls. and @pd>"20020417"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 10:55
S6	327	257/778.ccls. and @pd>"20020417"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 11:03
S7	77	257/713.ccls. and @pd>"20020417"	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 11:10
S8	1735	257/676.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 15:41
S9	1275	257/690.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 15:55
S10	792	257/780.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 16:10
S11	466	257/782.ccls.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 16:10

S12	121	((power adj2 device) or (power adj chip)) and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:26
S13	12	((power adj2 device) or (power adj chip)) and leadframe and (solder adj (ball or bump))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 17:54
S14	163	((power adj2 device) or (power adj chip)) and (solder adj (ball or bump))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 17:57
S15	288	((power adj2 device) or (power adj chip)) and (solder adj (ball\$1 or bump\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:27
S16	49	((power adj2 device) or (power adj chip)) and (solder adj (ball\$1 or bump\$1)) and source and drain	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/01/09 17:59
S17	4	(power adj (chip or device)) and (solder adj ball\$1) and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 11:26
S18	2	(power adj module) and (solder adj ball\$1) and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 11:26
S19	24	(power adj (module or chip or device or die)) and (solder adj (ball\$1 or bump\$1)) and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 11:32
S20	25	(power adj (module or chip or device or die)) and (flip adj chip) and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 11:32
S21	41	438/613-616.ccls. and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 14:46

S22	46	257/737.ccls. and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 14:51
S23	707	257/666-677.ccls. and (solder adj (ball\$1 or bump\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 14:59
S24	545	228/180.22.ccls. and (solder adj (ball\$1 or bump\$1))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 15:00
S25	17	228/180.22.ccls. and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 15:01
S26	46	438/111.ccls. and leadframe	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 15:02
S27	109	438/111.ccls. and (bump or ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 15:09
S28	306	438/123.ccls. and (bump or ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2003/06/13 15:10
S29	31	((("5629835") or ("5637916") or ("5765280") or ("5789809") or ("6133634") or ("6294403") or ("6329713") or ("6469384") or ("6489678") or ("6566749") or ("6627991") or ("6633030") or ("6661082") or ("6624522") or ("3972062") or ("5789809") or ("6423623"))).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 12:12
S30	201	(leadframe (lead adj frame)) same dimple\$1	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 14:38

S31	6	(leadframe (lead adj frame)) same indentation\$1 same solder	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 12:23
S32	621	(leadframe (lead adj frame)) and ((die chip) with (MOSFET MOS))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 15:04
S33	397	(leadframe (lead adj frame)) and ((die chip) with MOSFET)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:29
S34	744	(leadframe (lead adj frame)) and (die chip) and MOSFET	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/04 15:48
S35	0	(leadframe (lead adj frame)) same solder same Ni-Pb	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/05 12:18
S36	7	(leadframe (lead adj frame)) same solder same Ni-Pd	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/05 12:21
S37	66	(leadframe (lead adj frame)) same solder same (Ni-Pd (nickel adj lead) NiPd (Ni adj alloy))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/05 12:26
S38	10	(leadframe (lead adj frame)) and (solder same (Ni-Pd (nickel-lead) NiPd))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/02/05 12:27
S39	2	("5629835").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 14:39
S40	2	("6627991").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 14:39

S41	2	("6344687").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 14:43
S42	18	((("6836023") or ("6806580") or ("6798044") or ("6753605") or ("6740541") or ("6731003") or ("6720642") or ("6696321") or ("6683375")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 14:48
S43	2	("6661082").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 14:53
S44	2	("6133634").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 14:55
S45	2	("6661082").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 14:59
S46	2	("4939316").PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 15:02
S47	12	((("4939316") or ("5155299") or ("4965227") or ("4677526") or ("5241133") or ("4581680")).PN.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 15:02
S48	641	(leadframe (lead adj frame)) and ((die chip) with (MOSFET MOS))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 15:10
S49	263	(leadframe (lead adj frame)) and ((die chip) with (MOSFET MOS)) and (bump bumps ball balls)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/10/15 18:33
S50	9040	(die chip) with (solder adj (ball balls))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 15:54

S51	5693	(die chip) near5 (solder adj (ball balls))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 15:55
S52	3833	(die chip) near3 (solder adj (ball balls))	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/05/10 15:56